	Туре	L#	Hits	Search Text	DBs	Time Stamp	C o m m e nt	Er ror De fin iti on	
1	BRS	L1	0	(clean\$3 or etch\$3) same semicondcutor same (oxoethylene or oxypropylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 15:11			0
2	BRS	L8	170	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 17:58			0
3	BRS	L15	0	8 and "19991004"	USPAT; US-PGPUB EPO; JPO; DERWENT; IBM_TDB	2002/06/01 11:18			0
4	BRS	L22	136	8 and @pd<=19991004	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	[;] 2002/06/01 13:22			0
5	BRS	L29	2	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same (H2O or water) same ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide))	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	12.00			0
6	BRS	S L36	3 0	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same (H2O or water) same ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide)) same ("hydrogen peroxide" or H2O2 or peroxide)	US-PGPUI	2002/06/0			
7	BR	S L4	3 22	(clean\$3 or etch\$3) and (oxoethylene or oxypropylene) and (H2O or water) and ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide)) and ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	. ZUUZ/UO/U	1	***************************************	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	m	Er ror De fin iti on	ro rs
}	BRS	L	50	7	43 and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 13:11			0
9	BRS	L	57	165	43 and @pd<=19991004	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	2002/06/01 14:29			0
10	BRS	SL	.64	4	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	³ , 2002/06/01 13:27			0
11	BR	SIL	_71	46	(clean\$3 or etch\$3) and (oxoethylene or oxypropylene) and ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPUI EPO; JPO DERWEN ^T IBM_TDB	3; 2002/06/01 13:28			0
12	BR	S	L92	2 33	1 71 and @pd<=19991004	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	B; 2002/06/0 T;	1		0
1;	3 BF	RS	L9 ¹	9 0	92 and 438/\$.ccls.	USPAT; US-PGPL EPO; JPC DERWEN IBM_TDB	T; 10.50	1		
1	4 Bi	 RS	<u>L</u> 1	06 1	7 92 and 134/\$.ccls.	DERWEN IBM_TDE	√T; 10.33)1		
1	15 B	RS		113 1	92 and 216/\$.ccls.	USPAT; US-PGP EPO; JP DERWE IBM_TD	NT; 10.47	01		

	Тур	e I	∟#		lits		Search Text	DBs	Time Stamp	C o m m e nt	iti	ro rs
6	BRS	} L	12	20 3	38	92		USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	2002/06/01 16:51			0
7	BR	S	L1:	27	17	10	06 and @pd<=19991004	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	³ , 2002/06/01 , 14:38			0
18	BR	S	L1	34	1	1	13 and @pd<=19991004	USPAT; US-PGPUI EPO; JPO; DERWEN IBM_TDB		1		0
19	BF	RS	Ľ	141	38	3 1	20 and @pd<=19991004	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB		1		0
20	BI	RS	L	14	8 9	7	(clean\$3 or etch\$3) same (composition or pH or component or concentration) same (variable or parameter) same semiconductor	USPAT; US-PGPU EPO; JPC DERWEN IBM_TDB	IT; 10.12)1		
2	1 B	RS	3 1	_15	55 7	'21	(clean\$3 or etch\$3) same (composition or pH or component) same (variable or parameter or vary\$3 or chang\$3 or alter\$6) same semiconductor	EPU, JP	VT; 10.10	01		(
2	2 E	3R	S		62	123 3	(clean\$3 or etch\$3) same (composition or pH or component of mole) same (variable or parameter or vary\$3 or chang\$3 or alter\$6) same semiconductor	USPAT; or US-PGP EPO; JP DERWE IBM_TD	NT;	/01		
2	23	BR	S	L1	69	796	162 and @pd<=19991004	USPAT; US-PGF EPO; JF DERWE IBM_TD	:NT; 10.33	5/01		

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	C o m m e nt	iti	ro rs
24	BRS	L1	176	623	(clean\$3 or etch\$3) same (component or mole) same (variable or parameter or vary\$3 or chang\$3 or alter\$6) same semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 16:33			0
25	BRS	L	183	370	176 and @pd<=19991004	USPAT; US-PGPUB EPO; JPO; DERWENT; IBM_TDB	2002/06/01 16:33			0
26	BRS		.190	03	183 and 438/745	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	2002/06/01 16:35			0
27	BRS	3 L	_19	7 10	183 and 438/\$.ccls.	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	3, 2002/06/01 , 16:36			0
28	BRS	S	L20)4 10	183 and 134/\$.ccls.	USPAT; US-PGPUI EPO; JPO; DERWENT IBM_TDB	3; 2002/06/01 16:45			0
29	BR	S	L2 ⁻	11 36	183 and 216/\$.ccls.	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	B; 2002/06/0 16:48	1		
3	0 BR	:S	L2	18 20	64 183 not 197	USPAT; US-PGPU EPO; JPC DERWEN IBM_TDB	T; 10.49	1		
3	1 BF	RS	L2	225 1	3 211 not 197	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDE	IT;)1		

	Туре	L#	Hits	Search Text	DBs	Time Stamp	C o m m e nt s	Er ror De fin iti on	Er ro rs
32	BRS	L232	11	183 and 252/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 17:00			0